#### features

- Dual 12-Bit Voltage Output DAC
- Programmable Settling Time
  - 3 μs in Fast Mode
  - 10  $\mu$ s in Slow Mode
- Compatible With TMS320 and SPI Serial Ports
- Differential Nonlinearity <0.5 LSB Typ</li>
- Monotonic Over Temperature
- Direct Replacement for TLC5618A (C and I Suffixes)
- Available in Q-Temp Automotive
   HighRel Automotive Applications
   Configuration Control/Print Support
   Qualification to Automotive Standards

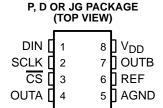
#### description

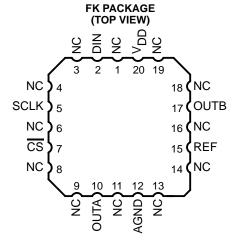
The TLV5618A is a dual 12-bit voltage output DAC with a flexible 3-wire serial interface. The serial interface is compatible with TMS320, SPI™, QSPI™, and Microwire™ serial ports. It is programmed with a 16-bit serial string containing 4 control and 12 data bits.

The resistor string output voltage is buffered by an x2 gain rail-to-rail output buffer. The buffer features a Class-AB output stage to improve stability and reduce settling time. The programmable settling time of the DAC allows the designer to optimize speed versus power dissipation.

#### applications

- Digital Servo Control Loops
- Digital Offset and Gain Adjustment
- Industrial Process Control
- Machine and Motion Control Devices
- Mass Storage Devices





Implemented with a CMOS process, the device is designed for single supply operation from 2.7 V to 5.5 V. It is available in an 8-pin SOIC package in standard commercial and industrial temperature ranges.

The TLV5618AC is characterized for operation from  $0^{\circ}$ C to  $70^{\circ}$ C. The TLV5618AI is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C. The TLV5618AQ is characterized for operation from  $-40^{\circ}$ C to  $125^{\circ}$ C. The TLV5618AM is characterized for operation from  $-55^{\circ}$ C to  $125^{\circ}$ C.

#### AVAILABLE OPTIONS

		PACK	AGE	
TA	PLASTIC DIP (P)	SOIC (D)	CERAMIC DIP (JG)	20 PAD LCCC (FK)
0°C to 70°C	TLV5618ACP	TLV5618ACD	_	_
-40°C to 85°C	TLV5618AIP	TLV5618AID	_	_
-40°C to 125°C	_	TLV5618AQD TLV5618AQDR		_
−55°C to 125°C	_	_	TLV5618AMJG	TLV5618AMFK



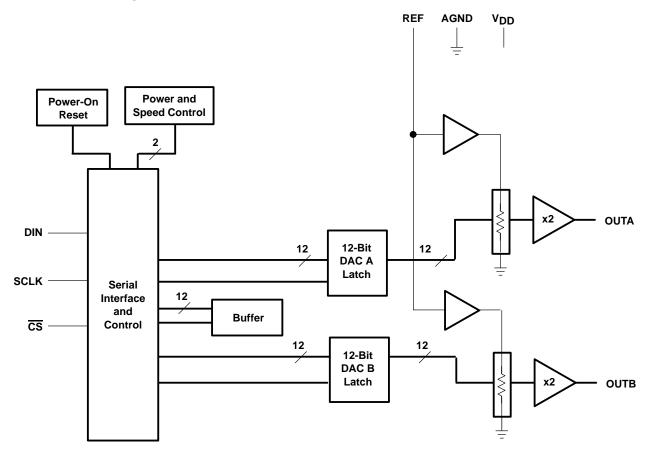
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Microwire is a trademark of National Semiconductor Corporation.



# functional block diagram



#### **Terminal Functions**

TERMI	NAL	I/O/D	DESCRIPTION
NAME	NO.	I/O/P	DESCRIPTION
AGND	5	Р	Ground
CS	3	I	Chip select. Digital input active low, used to enable/disable inputs.
DIN	1	I	Digital serial data input
OUTA	4	0	DAC A analog voltage output
OUTB	7	0	DAC B analog voltage output
REF	6	I	Analog reference voltage input
SCLK	2	I	Digital serial clock input
$V_{DD}$	8	Р	Positive power supply

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (V <sub>DD</sub> to AGND)	
Reference input voltage range	$- 0.3 \text{ V to V}_{DD} + 0.3 \text{ V}$
Digital input voltage range	– 0.3 V to $V_{DD}$ + 0.3 V
Operating free-air temperature range, T <sub>A</sub> : TLV5618AC	0°C to 70°C
TLV5618AI	–40°C to 85°C
TLV5618AQ	–40°C to 125°C
TLV5618AM	–55°C to 125°C
Storage temperature range, T <sub>sta</sub>	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### **DISSIPATION RATING TABLE**

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C <sup>‡</sup>	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	635 mW	5.08 mW/°C	407 mW	330 mW	127 mW
FK	1375 mW	11.00 mW/°C	880 mW	715 mW	275 mW
JG	1050 mW	8.40 mW/°C	672 mW	546 mW	210 mW

This is the inverse of the traditional junction-to-ambient thermal resistance (ROJA). Thermal resistances are not production tested and are for informational purposes only.

# recommended operating conditions

		MIN	NOM	MAX	UNIT	
Owner houself a real V	V <sub>DD</sub> = 5 V	4.5	5	5.5	.,	
Supply voltage, V <sub>DD</sub>	V <sub>DD</sub> = 3 V	2.7	3	3.3	V	
Power on reset		0.55		2	V	
1 Pale Level & Stall Secret code as A	V <sub>DD</sub> = 2.7 V	2			.,	
High-level digital input voltage, V <sub>IH</sub>	V <sub>DD</sub> = 5.5 V	2.4			V	
Levels at digital involved to a V	V <sub>DD</sub> = 2.7 V			0.6	.,	
Low-level digital input voltage, V <sub>IL</sub>	V <sub>DD</sub> = 5.5 V			1	٧	
Defendance valled to V to DEE torreited	V <sub>DD</sub> = 5 V (see Note 1)	AGND	2.048	V <sub>DD</sub> -1.5		
Reference voltage, V <sub>ref</sub> to REF terminal	V <sub>DD</sub> = 3 V (see Note 1)	AGND	1.024	V <sub>DD</sub> -1.5	V	
Load resistance, R <sub>L</sub>		2			kΩ	
Load capacitance, C <sub>L</sub>				100	pF	
Clock frequency, f(CLK)				20	MHz	
	TLV5618AC	0		70		
Operating free-air temperature, T <sub>A</sub>	TLV5618AI	-40		85	°С	
	TLV5618AQ	-40		125	C	
	TLV5618AM	-55		125		

NOTE 1: Due to the x2 output buffer, a reference input voltage  $\geq$  (VDD-0.4 V)/2 causes clipping of the transfer function.



# **TLV5618A** 2.7-V TO 5.5-V LOW-POWER DUAL 12-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS230H - JULY 1999 - REVISED JULY 2002

### electrical characteristics over recommended operating conditions (unless otherwise noted)

#### power supply

	PARAMETER	TEST C	ONDITIONS			MIN	TYP	MAX	UNIT
I <sub>DD</sub>		No load, All inputs = AGND or V <sub>DD</sub> , DAC latch = All ones	V <sub>DD</sub> = 4.5 V to		Fast		1.8	2.5	A
			5.5 V	C & I	Slow		0.8	1	mA
	Power supply current		V <sub>DD</sub> = 2.7 V to	suffixes	Fast		1.6	2.2	A
			3.3 V		Slow		0.6	0.9	mA
			V <sub>DD</sub> = 2.7 V to M & Q 5.5 V suffixe:	M & Q	Fast		1.8	2.3	A
				suffixes	Slow		0.8	1	mA
	Power down supply cur	rrent					1		μΑ
DODD		ratio	Zero scale, See Note 2				-65		5
PSRR	Power supply rejection		Full scale, See Note 3				-65		dB

NOTES: 2. Power supply rejection ratio at zero scale is measured by varying V<sub>DD</sub> and is given by:

 $PSRR = 20 \log [(E_{ZS}(V_{DD}max) - E_{ZS}(V_{DD}min)/V_{DD}max]]$ 

3. Power supply rejection ratio at full scale is measured by varying V<sub>DD</sub> and is given by:

 $PSRR = 20 \log [(E_G(V_{DD}max) - E_G(V_{DD}min)/V_{DD}max]]$ 

#### static DAC specifications

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
	Resolution				12			bits
INL	Integral nonlinearity	See Note 4			±2	±4	LSB	
DNL	Differential nonlinearity	See Note 5				±0.5	±1	LSB
EZS	Zero-scale error (offset error at zero scale)	See Note 6					±12	mV
E <sub>ZS</sub> (TC)	Zero-scale-error temperature coefficient	See Note 7				3		ppm/°C
				$V_{DD} = 4.5 \text{ V} - 5.5 \text{ V}$			±0.29	
EG	Gain error	See Note 8	C & I suffixes	$V_{DD} = 2.7 \text{ V} - 3.3 \text{ V}$			±0.6	% full scale V
			M & Q suffixes	$V_{DD} = 2.7 \text{ V} - 5.5 \text{ V}$			±0.6	Scale v
E <sub>G</sub> (TC)	Gain-error temperature coefficient	See Note 9				1		ppm/°C

- NOTES: 4. The relative accuracy of integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale, excluding the effects of zero-code and full-scale errors.
  - 5. The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1-LSB amplitude change of any two adjacent codes.
  - 6. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
  - 7. Zero-scale-error temperature coefficient is given by:  $E_{ZS}$  TC =  $[E_{ZS}$  ( $T_{max}$ )  $E_{ZS}$  ( $T_{min}$ )]/2 $V_{ref}$  × 10<sup>6</sup>/( $T_{max}$   $T_{min}$ ).

  - 8. Gain error is the deviation from the ideal output ( $2V_{ref} 1$  LSB) with an output load of 10 k $\Omega$ . 9. Gain temperature coefficient is given by: E<sub>G</sub> T<sub>C</sub> = [E<sub>G</sub> ( $T_{max}$ ) E<sub>g</sub> ( $T_{min}$ )]/ $2V_{ref} \times 10^6$ /( $T_{max} T_{min}$ ).

#### output specifications

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
۷o	Output voltage range	$R_L = 10 \text{ k}\Omega$	0		V <sub>DD</sub> -0.4	V
	Output load regulation accuracy	$V_O = 4.096 \text{ V}, 2.048 \text{ V},$ $R_L = 2 \text{ k}\Omega \text{ to } 10 \text{ k}\Omega$			±0.29	% FS



# electrical characteristics over recommended operating conditions (unless otherwise noted) (continued)

#### reference input

	PARAMETER	TEST CONDITIONS	TEST CONDITIONS		P MAX	UNIT
٧ı	Input voltage range			0	V <sub>DD-1.5</sub>	V
RĮ	Input resistance	10		ΜΩ		
$C_I$	Input capacitance				5	pF
	Defense as input handwidth	DEE 0.0 V . 4.004 V de	Fast	1	3	MHz
	Reference input bandwidth	EF = 0.2 V <sub>pp</sub> + 1.024 V dc Slow		52	5	kHz
	Reference feedthrough	REF = 1 V <sub>pp</sub> at 1 kHz + 1.024 V dc (see Note	F = 1 V <sub>pp</sub> at 1 kHz + 1.024 V dc (see Note 10) -80		dB	

NOTE 10: Reference feedthrough is measured at the DAC output with an input code = 0x000.

#### digital inputs

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
lн	High-level digital input current	$V_I = V_{DD}$			1	μΑ
IL	Low-level digital input current	V <sub>I</sub> = 0 V	-1			μΑ
Ci	Input capacitance			8		pF

### analog output dynamic performance

	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
	Output as the office fall as also	D 4010	O 400 "E O Note 44	Fast		1	3	_
ts(FS)	Output settling time, full scale	$R_L = 10 \text{ k}\Omega$	$C_L = 100 \text{ pF}$ , See Note 11	Slow		3	10	μs
	Output and a substantian and a to and a	D 4010	0 400 = F 0 - Note 40	Fast 1		_		
ts(CC)	Output settling time, code to code	$R_L = 10 \text{ k}\Omega$	$C_L = 100 \text{ pF}$ , See Note 12	Slow		2		μs
0.0		<b>D</b> 4010	0 400 5 0 11 / 40	Fast		3		
SR	Slew rate	Ri = 10 kO	Slow		0.5		V/μs	
	Glitch energy	DIN = 0  to  1,	FCLK = 100 kHz, CS = V <sub>DD</sub>			5		nV-s
SNR	Signal-to-noise ratio					76		
SINAD	Signal-to-noise + distortion	f <sub>S</sub> = 102 kSPS,	$f_{out} = 1 \text{ kHz},  R_L = 10 \text{ k}\Omega,$			68		ı.
THD	Total harmonic distortion	C <sub>L</sub> = 100 pF	_			-68		dB
SFDR	Spurious free dynamic range					72		

- NOTES: 11. Settling time is the time for the output signal to remain within  $\pm 0.5$  LSB of the final measured value for a digital input code change of 0x020 to 0xFDF and 0xFDF to 0x020 respectively. Not tested, assured by design.
  - 12. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of one count. Not tested, assured by design.
  - 13. Slew rate determines the time it takes for a change of the DAC output from 10% to 90% of full-scale voltage.



# digital input timing requirements

				MIN	NOM	MAX	UNIT
		0 11 "	V <sub>DD</sub> = 5 V	5			
tsu(CS-CK)	Setup time, CS low before first negative SCLK edge	C and I suffixes	$V_{DD} = 3 V$	10			ns
, ,		Q and M suffixes	,	10	NOM MAX	ns	
tsu(C16-CS)	Setup time, 16 <sup>th</sup> negative SCLK edge before CS rising	edge		10			ns
<sup>t</sup> w(H)	SCLK pulse width high			25			ns
t <sub>w(L)</sub>	SCLK pulse width low			25			ns
, ,	Setup time, data ready before SCLK falling edge	C and I suffixes	V <sub>DD</sub> = 5 V	5			
tsu(D)			V <sub>DD</sub> = 3 V	10			ns
. ,		Q and M suffixes	;	8	5 10 10 10 25 25 5 10		
		C and I auffine	$V_{DD} = 5 V$	5			
<sup>t</sup> h(D)	Hold time, data held valid after SCLK falling edge	C and I suffixes	V <sub>DD</sub> = 3 V	10			ns
		Q and M suffixes	-	10			
		•	V <sub>DD</sub> = 5 V	25			
<sup>t</sup> h(CSH)	Hold time, CS high between cycles		V <sub>DD</sub> = 3 V	50			ns

# timing requirements

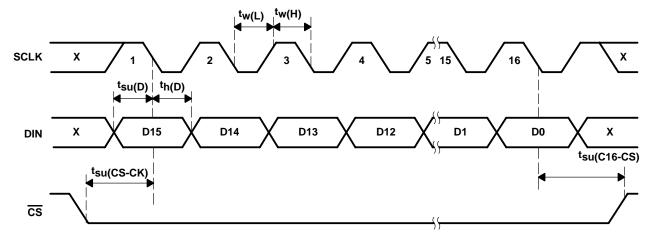


Figure 1. Timing Diagram



#### TYPICAL CHARACTERISTICS

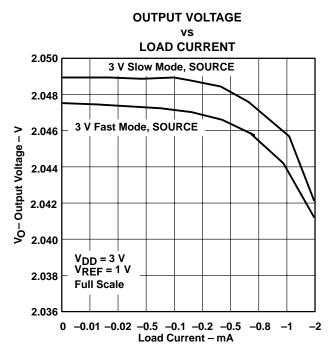
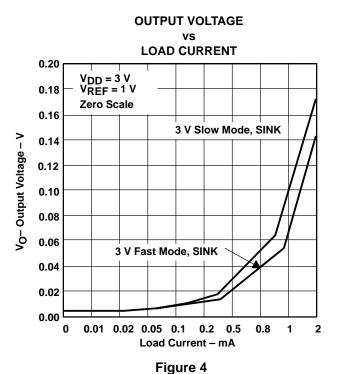
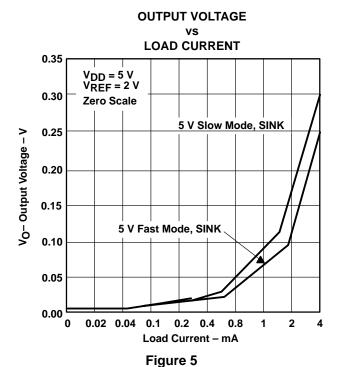


Figure 2



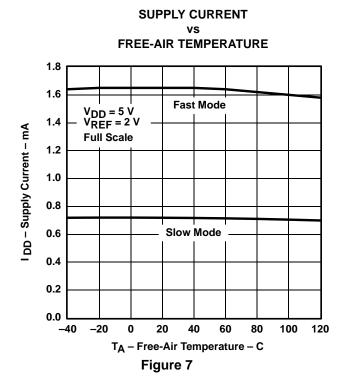
**OUTPUT VOLTAGE** vs **LOAD CURRENT** 4.105  $V_{DD} = 5 V$ VREF = 2 V 5 V Slow Mode, SOURCE 4.100 **Full Scale** Vo-Output Voltage - V 4.095 5 V Fast Mode, SOURCE 4.090 4.085 4.080 4.075 4.070 0 -0.02 -0.04 -0.1 -0.2 -0.4 -0.8 -2 Load Current - mA

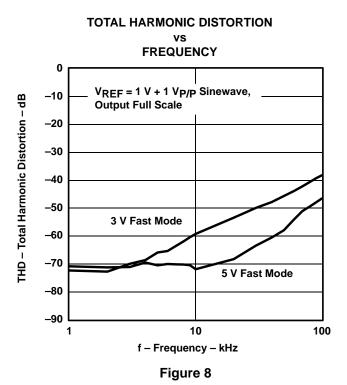
Figure 3

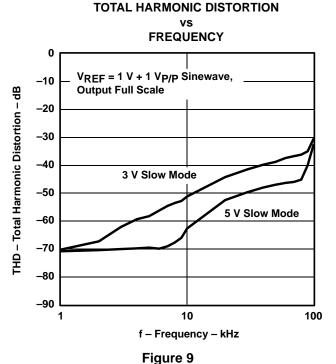


#### **TYPICAL CHARACTERISTICS**

#### **SUPPLY CURRENT** FREE-AIR TEMPERATURE 1.8 V<sub>DD</sub> = 3 V V<sub>REF</sub> = 1 V 1.6 Full Scale **Fast Mode** 1.4 I DD - Supply Current - mA 1.2 1.0 8.0 Slow Mode 0.6 0.4 0.2 0.0 -40 -20 0 20 40 60 80 100 120 T<sub>A</sub> - Free-Air Temperature - C Figure 6







#### **TYPICAL CHARACTERISTICS**

# INTEGRAL NONLINEARITY ERROR

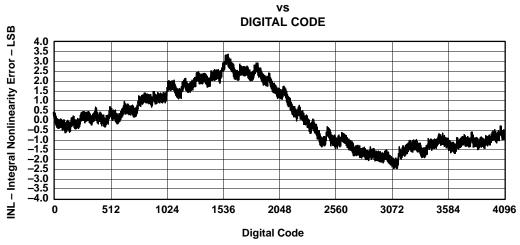


Figure 10

#### **DIFFERENTIAL NONLINEARITY ERROR**

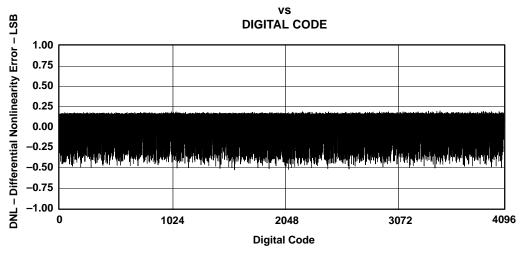


Figure 11

#### APPLICATION INFORMATION

#### general function

The TLV5618A is a dual 12-bit, single-supply DAC, based on a resistor-string architecture. It consists of a serial interface, a speed and power down control logic, a resistor string, and a rail-to-rail output buffer.

The output voltage (full scale determined by the reference) is given by:

$$2 REF \frac{CODE}{2^n} [V]$$

Where REF is the reference voltage and CODE is the digital input value within the range of 0<sub>10</sub> to 2<sup>n</sup>–1, where n=12 (bits). The 16-bit data word, consisting of control bits and the new DAC value, is illustrated in the data format section. A power-on reset initially resets the internal latches to a defined state (all bits zero).

#### serial interface

A falling edge of  $\overline{CS}$  starts shifting the data bit-per-bit (starting with the MSB) to the internal register on the falling edges of SCLK. After 16 bits have been transferred or  $\overline{CS}$  rises, the content of the shift register is moved to the target latches (DAC A, DAC B, BUFFER, CONTROL), depending on the control bits within the data word.

Figure 12 shows examples of how to connect the TLV5618A to TMS320, SPI, and Microwire.

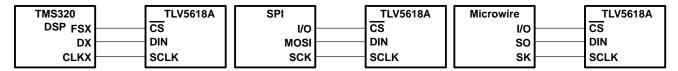


Figure 12. Three-Wire Interface

Notes on SPI and Microwire: Before the controller starts the data transfer, the software has to generate a falling edge on the pin connected to CS. If the word width is 8 bits (SPI and Microwire) two write operations must be performed to program the TLV5618A. After the write operation(s), the holding registers or the control register are updated automatically on the next positive clock edge following the 16th falling clock edge.

#### serial clock frequency and update rate

The maximum serial clock frequency is given by:

$$f_{sclkmax} = \frac{1}{t_{whmin} + t_{wlmin}} = 20 \text{ MHz}$$

The maximum update rate is:

$$f_{updatemax} = \frac{1}{16(t_{whmin} + t_{wlmin})} = 1.25 \text{ MHz}$$

Note that the maximum update rate is just a theoretical value for the serial interface, as the settling time of the TLV5618A should also be considered.



#### APPLICATION INFORMATION

#### data format

The 16-bit data word for the TLV5618A consists of two parts:

• Program bits (D15..D12)

New data (D11..D0)

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R1	SPD	PWR	R0	MSB					12 Da	ta bits					LSB

SPD: Speed control bit  $1 \rightarrow$  fast mode  $0 \rightarrow$  slow mode PWR: Power control bit  $1 \rightarrow$  power down  $0 \rightarrow$  normal operation On power up, SPD and PWD are reset to 0 (slow mode and normal operation)

The following table lists all possible combinations of register-select bits:

#### register-select bits

R1	R0	REGISTER
0	0	Write data to DAC B and BUFFER
0	1	Write data to BUFFER
1	0	Write data to DAC A and update DAC B with BUFFER content
1	1	Reserved

The meaning of the 12 data bits depends on the register. If one of the DAC registers or the BUFFER is selected, then the 12 data bits determine the new DAC value:

#### examples of operation

Set DAC A output, select fast mode:

Write new DAC A value and update DAC A output:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	1	0	0					Nev	v DAC A	output va	alue				

The DAC A output is updated on the rising clock edge after D0 is sampled.

Set DAC B output, select fast mode:

Write new DAC B value to BUFFER and update DAC B output:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	1	0	0	New BUFFER content and DAC B output value											

The DAC A output is updated on the rising clock edge after D0 is sampled.

- Set DAC A value, set DAC B value, update both simultaneously, select slow mode:
  - 1. Write data for DAC B to BUFFER:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	1	New DAC B value											

2. Write new DAC A value and update DAC A and B simultaneously:

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	0	0	0	New DAC A value											



#### APPLICATION INFORMATION

#### examples of operation (continued)

Both outputs are updated on the rising clock edge after D0 from the DAC A data word is sampled.

Set power-down mode:

ĺ	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
ſ	Χ	Х	1	Х	Х	Х	Χ	Х	Х	Х	Х	Х	Х	Х	Х	Х

X = Don't care

# linearity, offset, and gain error using single ended supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset, the output voltage may not change with the first code, depending on the magnitude of the offset voltage.

The output amplifier attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground and clamps the output at 0 V.

The output voltage then remains at zero until the input code value produces a sufficient positive output voltage to overcome the negative offset voltage, resulting in the transfer function shown in Figure 13.

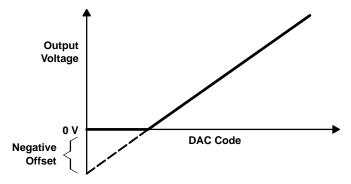


Figure 13. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces this breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below the ground rail.

For a DAC, linearity is measured between zero-input code (all inputs 0) and full-scale code (all inputs 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity is measured between full-scale code and the lowest code that produces a positive output voltage.



#### APPLICATION INFORMATION

#### definitions of specifications and terminology

#### integral nonlinearity (INL)

The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.

#### differential nonlinearity (DNL)

The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.

#### zero-scale error (E<sub>7S</sub>)

Zero-scale error is defined as the deviation of the output from 0 V at a digital input value of 0.

#### gain error (E<sub>G</sub>)

Gain error is the error in slope of the DAC transfer function.

#### total harmonic distortion (THD)

THD is the ratio of the rms value of the first six harmonic components to the value of the fundamental signal. The value for THD is expressed in decibels.

#### signal-to-noise ratio + distortion (S/N+D)

S/N+D is the ratio of the rms value of the output signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

# spurious free dynamic range (SFDR)

Spurious free dynamic range is the difference between the rms value of the output signal and the rms value of the largest spurious signal within a specified bandwidth. The value for SFDR is expressed in decibels.



27-Apr-2012

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-9955701Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9955701QPA	ACTIVE	CDIP	JG	8	1	TBD	Call TI	Call TI	
TLV5618ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TLV5618ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TLV5618AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TLV5618AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TLV5618AMFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
TLV5618AMJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
TLV5618AMJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
TLV5618AQD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AQDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TLV5618AQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

# PACKAGE OPTION ADDENDUM



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(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF TLV5618A, TLV5618AM:

Catalog: TLV5618A

Enhanced Product: TLV5618A-EP, TLV5618A-EP

Military: TLV5618AM

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications



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• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All difficultions are florifinal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV5618ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV5618AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLV5618AQDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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#### \*All dimensions are nominal

1	7 III GITTIOTIOTOTIO GITO TIOTITITICI							
	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	TLV5618ACDR	SOIC	D	8	2500	346.0	346.0	29.0
	TLV5618AIDR	SOIC	D	8	2500	346.0	346.0	29.0
	TLV5618AQDR	SOIC	D	8	2500	346.0	346.0	29.0

# JG (R-GDIP-T8)

#### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# P (R-PDIP-T8)

# PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



# D (R-PDSO-G8)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



# D (R-PDSO-G8)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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